

Pseudoplastic paste

(25 °C, D = 100/s)

6 months from date of shipment with correct

container

storage (in a dry, cool $(5 - 25 \ ^{\circ}C)$ and dark

82.5 % ± 1.5 %

Up to 20 cm/s

place with

tightly shut).

25 - 45 Pas

Technical Data Sheet



THICK FILM MATERIALS

Product Type: Conductors Product Name: C2210

Typical Properties (Paste)

Palladium Alloy Conductor Paste

Form

Viscosity

Solids

Printing Speed

Shelf Life

Description

C2210 is a lead free 0.8:1 Ag / Pd pre- alloyed conductor paste which exhibits high reliability and remarkable fine line resolution.

C2210 has an enriched Pd content to address increased demands by low sulfur fuel applications and greatly reduces risk of silver migration.

Key Benefits

- Excellent conductivity, leach resistance and resistance to silver migration
- Exceptional chemical and physical wear resistance in use as a track material for sliders
- Low cost alternative to gold in stringent fuel sensor application
- Free of lead, cadmium and nickel

Processing

1) Spatulate well prior to processing.

When stored in a refrigerator, the paste should have acquired room temperature before being opened, to avoid condensation.

- 2) Print through a 200 325 mesh stainless steel screen.
- 3) Level at room temperature for 5 10 minutes.
- 4) Dry at 150 °C for 10 20 minutes.
- 5) Fire at 850 °C (peak) for 10 minutes, and with a total firing cycle time of c. 30 60 minutes.

Typical Properties (Fired) ¹	
Fired Film Thickness ² (FFT)	8.5 – 12.0 µm
Line Definition	≥ 125 µm
Resistivity ²	$\leq 130~\text{m}\Omega/\Box$ (FFT: 12 $\mu\text{m})$
Aged Adhesion (Sn62/Pb36/Ag2)	≥ 20 N (16 hrs, 25 °C)
Leach Resistance	Not available

Thinner

HVS 100

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Palladium Alloy Conductor Paste

Legend:

¹⁾ Typical properties based on laboratory test methods. For optimum results all materials should be fired in a profiled furnace supplied with dried, hydrocarbon and other contaminant free air (PP-1).

 $^{2)}$ Measured after printing with a 325 mesh steel screen; screen thickness and emulsion thickness combined was c. 75 μ m, and the resultant printed track was 500 μ m wide.

** See the data sheet issue date (DD/MM/YY) as reference of validity of latest edition which is available on request

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